

Flip Chip International Appoints Jay Grover as Vice President – Operations

PHOENIX, Arizona, December 1, 2004---FlipChip International LLC announced today that it has appointed Jay Grover as its Vice President of Operations for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona. Mr. Jay Grover will report to Bob Forcier, President and CEO of FlipChip International.

Prior to joining FlipChip International, Mr. Grover has demonstrated substantial leadership, operational and global logistics experience in his 25 years as a senior manager in high volume electronic manufacturing. Mr. Grover's most recent experience includes President of Neltec, Inc. a wholly owned subsidiary of Park Electrochemical with multiple manufacturing facilities. Mr. Grover has held positions with Nelco Technology, Inc. high density interconnect business, Neltec, S.A. RF microwave materials business in Lannemezan France, Arlon's high-performance circuitry materials facility located in Rancho Cucamonga, California and Arlon's RF microwave materials facility located in Bear, Delaware. Mr. Bruce Bowers, the previous VP Operations, has accepted the Sr. Vice President of Strategic Development for FlipChip International also reporting to Bob Forcier.

Bob Forcier, President and CEO of FlipChip International stated "We are very pleased to have Jay Grover join FlipChip International as our Vice-President Operations. Jay's extensive experience in operations and global logistics will bring substantial leadership skills, prepare us for our 2005 growth plans both organically and with potential acquisitions in the future."

Mr. Grover said, "I am excited about joining the FlipChip International team. I enjoy the challenge of engaging with a very skilled and willing workforce with substantial growth plans for wafer scale packaging and wafer bumping services. I am also very excited with the FlipChip International potential for future growth in new products, especially in the areas of high speed wireless devices such as flip chip solutions for camera phones and video phones."

FlipChip International, LLC is privately supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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